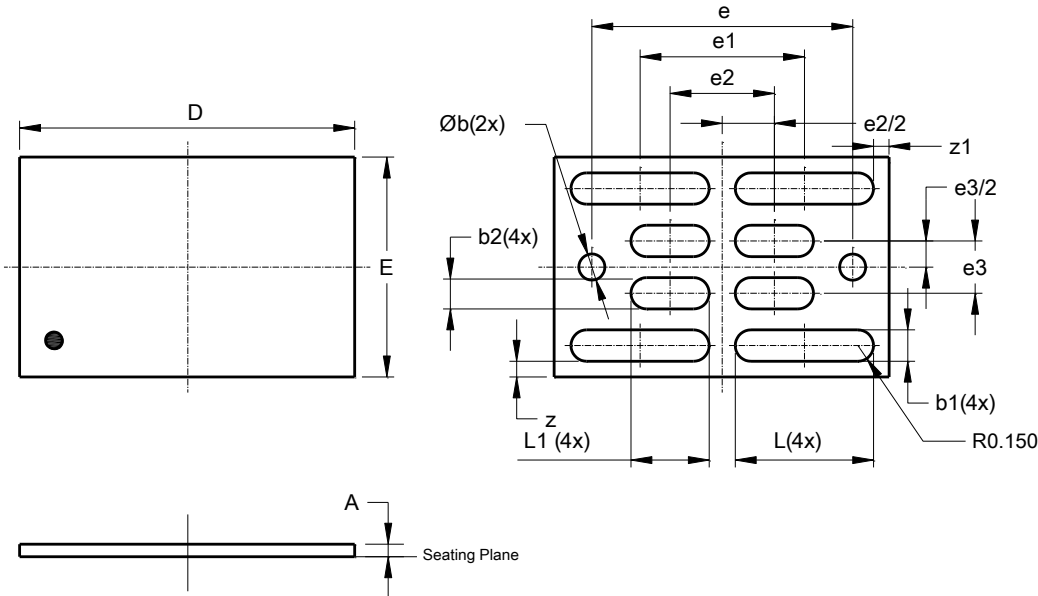


Package Outline Dimensions

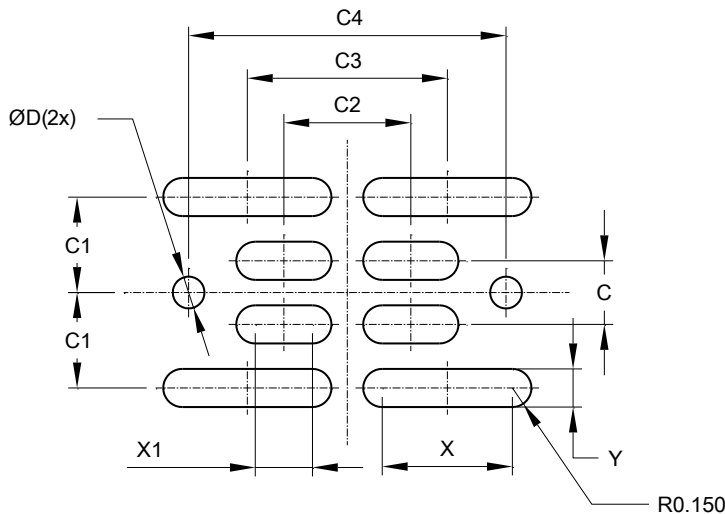
X4-DSN3221-10



X4-DSN3221-10			
Dim	Min	Max	Typ
A	--	0.150	0.120
b	0.220	0.280	0.250
b1	0.270	0.330	0.300
b2	0.270	0.330	0.300
D	3.170	3.230	3.200
E	2.070	2.130	2.100
e	2.500 BSC		
e1	1.575 BSC		
e2	1.000 BSC		
e3	0.500 BSC		
L	1.295	1.355	1.325
L1	0.720	0.780	0.750
z	0.120	0.180	0.150
z1	0.120	0.170	0.150
All Dimensions in mm			

Suggested Pad Layout

X4-DSN3221-10



Dimensions	Value (in mm)
C	0.500
C1	0.750
C2	1.000
C3	1.575
C4	2.500
D	0.250
X	1.025
X1	0.450
Y	0.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.